



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-07-17
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement
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Legal statement			
Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32MP233FAK3	EK79*505XXXY	A	9991	2025-07-17
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	364	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Not Applicable	NAC	SACN305	
Package designator	Package size	Number of instances	Shape	
BGA	14x14	424	Bulk solder	
Comment	Package : B0MP FC VFBGA 14X14 424B P0.5 DM01034187			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			false
Exemption Id.	Description		
,			

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EK79*505XXY		364.1023		5000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.000	mg	supplier	die	Silicon(Si)	7440-21-3		9.329	mg	932860	25620.82
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	500	13.73
				supplier	metallisation	Arsenic(As)	7440-38-2		0.000	mg	4	0.11
				supplier	metallisation	Copper(Cu)	7440-50-8		0.498	mg	49763	1366.73
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.000	mg	29	0.80
				supplier	metallisation	Silver(Ag)	7440-22-4		0.002	mg	196	5.38
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.005	mg	500	13.73
				supplier	metallisation	Tin(Sn)	7440-31-5		0.107	mg	10667	292.97
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	108	2.97
				supplier	metallisation	Tungsten(W)	7440-33-7		0.006	mg	550	15.11
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.014	mg	1399	38.42
				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	3424	94.04
Substrate (A32383)	Copper & Resin	105.305	mg	supplier	Solder Mask	Plastics PAK	Proprietary		3.141	mg	29826	8626.26
				supplier	Solder Mask	Barium sulphate	7727-43-7		1.254	mg	11905	3443.16
				supplier	Solder Mask	Plastic EP	Proprietary		0.806	mg	7653	2213.40
				supplier	Solder Mask	Silicon dioxide	7631-86-9		0.640	mg	6074	1756.72
				supplier	Solder Mask	Additives, not to declare	Proprietary		0.288	mg	2733	790.44
				supplier	Solder Mask	Talc	14807-96-6		0.192	mg	1822	526.96
				supplier	Solder Mask	Pigment portion, not to declare	Proprietary		0.038	mg	364	105.28
				supplier	Solder Mask	Inorganic Ingredient, not to declare	Proprietary		0.038	mg	364	105.28
				supplier	PP	Thermosetting resin (including filler)	Proprietary		20.110	mg	190964	55230.50
				supplier	PP	Glass Cloth	65997-17-3		13.406	mg	127310	36820.52
				supplier	Cu foil	Copper	7440-50-8		7.307	mg	69388	20068.36
				supplier	Cu Plating	Copper	7440-50-8		58.086	mg	551597	159532.56
Underfill (UA26)	Encapsulation Glue	1.900	mg	supplier	Underfill	p-(2,3-epoxypropoxy)-N, N-bis(2,3-epoxypropyl)a	5026-74-4		0.190	mg	100000	521.83
				supplier	Underfill	Bisphenol F type liquid epoxy resin	9003-36-5		0.190	mg	100000	521.83
				supplier	Underfill	Bisphenol A type liquid epoxy resin	25068-38-6		0.057	mg	30000	156.55
				supplier	Underfill	Amine type hardener	Proprietary		0.143	mg	75000	391.37
				supplier	Underfill	Carbon black	1333-86-4		0.010	mg	5000	26.09
				supplier	Underfill	Silicon dioxide	60676-86-0		1.235	mg	650000	3391.90
Encapsulation (EME-G760-SW)	Molding Compound	202.563	mg	supplier	Underfill	Additives	Proprietary		0.076	mg	40000	208.73
				supplier	Molding compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-di	85954-11-6		16.205	mg	80000	44506.74
				supplier	Molding compound	Phenol Resin A	9003-35-4		8.103	mg	40000	22253.37
				supplier	Molding compound	Phenol Resin B	Proprietary		8.103	mg	40000	22253.37
				supplier	Molding compound	Silica(Amorphous) A	60676-86-0		121.538	mg	600000	333800.52
				supplier	Molding compound	Silica(Amorphous) B	7631-86-9		40.513	mg	200000	111266.84
Solder balls (SACN305)	Other inorganic materials	44.334	mg	supplier	Molding compound	Metal Hydroxide	Proprietary		6.077	mg	30000	16690.03
				supplier	Molding compound	Carbon Black	1333-86-4		2.026	mg	10000	5563.34
				supplier	Solder Ball	Tin	7440-31-5		42.694	mg	963000	117258.03
				supplier	Solder Ball	Silver	7440-22-4		1.463	mg	33000	4018.19
				supplier	Solder Ball	Copper	7440-50-8		0.155	mg	3500	426.17
				supplier	Solder Ball	Nickel	7440-02-0		0.022	mg	500	60.88